



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/11/2016 8:10:51 AM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/11/2016 8:10:52 AM		TEXAS INSTRUMENTS

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